

Hong Kong-Shenzhen Innovation and Technology Park Limited

Tender Notice

1. Tender Number

Works Contract No.: WC/015

2. Subject

High Performance Computing Facilities at 1/F of Building 9

3. Description

The scope of services includes:

- a) Design of the high performance computing (HPC) facilities,
- b) Design, supply and installation of interior fitting-out works including front-of-house area, back-of-house area, data hall area, network operations centre (NOC),
- c) Design, supply and installation of building services installation to support the HPC facilities including power infrastructure, cooling infrastructure, uninterruptible power supply, all ancillary services and all associated builder's work,
- d) Any alternations required for ancillary services,
- e) Interfacing works with existing building systems, and
- f) Testing and commissioning.

The details of the scope of works shall refer to the Tender Documents. The Contract is scheduled to commence in early October 2026 tentatively.

4. Eligibility to Tender

Tenderers who satisfy **ALL** the minimum requirements stated in Annex A of this tender notice will be eligible to submit tenders.

5. Tender Issuance

Please complete Annex B of this tender notice and return to m1273@beria.com.hk for collection of Tender Documents. A formal invitation letter with Tender Documents will be sent by e-mail upon receipt of the completed Annex B of this notice. For enquiry, please send e-mail to m1273@beria.com.hk.

6. Submission Requirements

Please submit your tenders strictly in accordance with the requirements stipulated in the Tender Documents. You are required to submit the acknowledgement slip appended in the Invitation Letter on or before **18 August 2026** by email to m1273@beria.com.hk.

Tenderers are required to submit the Technical Submission and Price Submission in **two separate and sealed** envelopes in the Tender Box located at Hong Kong-Shenzhen Innovation and Technology Park Limited, Units 806 & 807, 8/F, Building 9, Research Road, Hong Kong-Shenzhen Innovation and Technology Park, Lok Ma Chau, Hong Kong according to the requirements stipulated in the Tender Documents **at any time between 9:00 a.m. and 12:00 noon (Hong Kong Time) on 14 September 2026**. Proposals not deposited within the aforesaid time or not deposited in the Tender Box will not be considered.

If tropical cyclone warning signal No. 8 or above or the black rainstorm warning signal is issued, or “extreme conditions after super typhoons” announced by the Government is/are in force at any time between 9:00 a.m. and 12:00 noon on the tender closing date, the tender closing time will be postponed to 12:00 noon on the first working day after the tropical cyclone warning signal No. 8 or the black rainstorm signal is cancelled, or the “extreme conditions after super typhoons” announced by the Government has/have ceased to be in force.

The Employer does not bind itself to accept any tender irrespective of whether the tender is the lowest bid or, where the assessment of the tenderers is based on marking scheme approach, the tender with the highest overall score.

Any qualification of the submission may cause your submission to be disqualified and the Employer reserves the right not to consider your submission further.

The Employer reserves the right to negotiate with any tenderer about the terms of the offer.

Minimum Requirements for Tender Submission

Tenderer must satisfy all minimum requirements listed below. In the event that tenderer does not satisfy all the minimum requirements, its tender submission shall be treated as non-conforming and shall not be considered further.

Item	Description of Minimum Requirements ^(Note 1, 4 & 5)
1	The tenderer should be a company registered under the Companies Ordinance in Hong Kong for at least three years counting from and including the tender closing date, or if this has been extended, the extended date.
2	The tenderer should have completed at least one contract for design and build works for: (i) high performance computing facilities; and/or (ii) data centre, with construction floor area not less than 500 m ² ^(Note 2) , within the last ten years counting from and including the original tender closing date, or if this has been extended, the extended date.
3	The tenderer should have completed at least one contract for design and build works for: (i) high performance computing facilities; and/or (ii) data centre, with construction floor area not less than HK\$45 million ^(Note 3) , within the last ten years counting from and including the original tender closing date, or if this has been extended, the extended date.

Notes:

- (1) The tenderer is allowed to use the same contract to satisfy both items 1 and 2 above.
- (2) The construction floor area of not less than 500 m² could be new building and/or interior fit-out works within a completed contract.
- (3) The contract value of not less than HK\$45 million could be new building and/or interior fit-out works within a completed contract.
- (4) The relevant project experience of all associated company(ies) of the tenderer will also be accepted. Sections 2, 13 to 15 of the Companies Ordinance (Cap. 622) are applicable to justify the relationships among these companies within the same group.
- (5) In the event that the relevant project experience is obtained by the tenderer in joint venture with other company(ies), the number of contracts and contract values of those relevant projects would be evaluated according to DEVB TC(W) 4/2014 and 4/2014A.

To : Beria Consultants Limited

Email : m1273@beria.com.hk

**Hong Kong-Shenzhen Innovation and Technology Park
High Performance Computing Facilities at 1/F of Building 9
Works Contract No. WC/015
Request for Collection of Tender Documents**

We refer to the Tender Notice for the Works Contract and would like to request for collection of Tender Documents. Please send us the relevant documents for our onward submission of tender.

From (Company Name) : _____

Signature : _____

(Authorized Signature)

Capacity of the Signatory : _____

Company Chop : _____

Date : _____

Office Address : _____

Email Contact : _____

Phone Number : _____

Business Card of Contact
Person :